

AMENDMENTS TO THE SPECIFICATION:

In the title:

Please change the title to read as follows:

MANUFACTURING METHOD OF A SEMICONDUCTOR DEVICE
UTILIZING A FLEXIBLE ADHESIVE TAPE.

Page 54:

Please substitute the following paragraph for the paragraph beginning at line 20.

The adhesive 50 used is an insulating adhesive which is ~~stronger~~weaker in its adhesion to an adhesive (first adhesive) 26 for bonding a tape 1a and copper foil than in its adhesion to the silicon substrate of the semiconductor element 4. Therefore, when the tape 1a is peeled from the insulating resin layer 6, the adhesive 50 and the tape 1a (or the adhesive (first adhesive) 26) are peeled from each other in such a manner that the adhesive 50 remains on a back surface of the semiconductor element 4.

Page 55:

Please substitute the following paragraph for the paragraph beginning at line 4.

The adhesive 50 may be substituted by an adhesive tape both surfaces of which are adhesive surfaces. The adhesive

which forms the adhesive surfaces is an insulating adhesive which is ~~stronger~~weaker in its adhesion to the adhesive (first adhesive) 26 for bonding the tape 1a and copper foil than in its adhesion to the semiconductor element 4 and the silicon substrate. Therefore, when the tape 1a is peeled from the insulating resin layer 6, the adhesive 50 and the tape 1a (or the adhesive (first adhesive) 26) are peeled from each other while allowing the insulating adhesive tape to remain on the back surface of the semiconductor element 4.